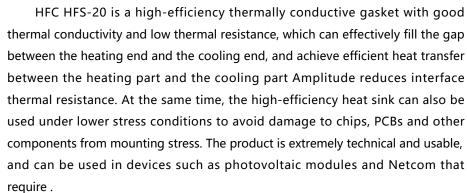
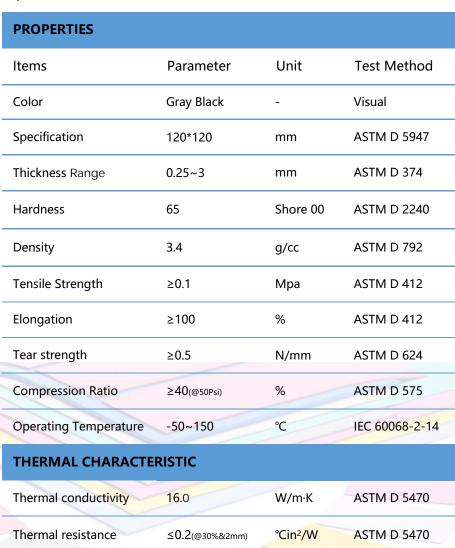
Innovative Materials Manufacturer

HFS- 20 series

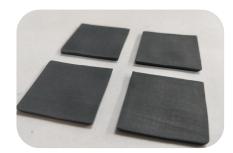
[Thermal Gap Filler]

DATA SHEET





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-Product picture-

FEATURES:

- High thermal conductivity and low thermal resistance
- Low stress assembly
- Good thermal stability
- Multiple thickness options, wide range of applications
- •Slight color difference on the surface is a product characteristic and does not affect performance

APPLICATIONS:

- •Satellite, radar and other military fields
- •Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- Wearable equipments

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: $\le 30 \,^{\circ}\text{C}$ STORAGE HUMIDITY: $\le 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE:

Under storage conditions: 2 year